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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Appl. No. : **10/734,195**
Applicant : **Kwun-Yao Ho et al.**
Filed : **December 15, 2003**
Title : **HIGH-DENSITY MULTICHIP MODULE**
PACKAGE
TC/A.U. : **2813**
Examiner : **BRYANT, DELORIS S**
Docket No. : **025796-00014**

RESPONSE UNDER 37 C.F.R. § 1.111

MAIL STOP AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

October 6, 2006

Sir:

In reply to the Official Action dated June 29, 2006, the period for response being extended from September 29, 2006 to October 29, 2006, by the attached Petition for Extension of Time, please amend the above-identified application as set forth below:

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 5 of this paper.